**삼성전자 CE/IM부문 현장실습 참가 신청서**

작성일 : 2020. 00. 00

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| **생년월일** | 000000 | **희망직무** | SW개발 / 회로개발 / 기구개발 中 택1 |
| **핸드폰** |  | **e-mail** |  |

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| --- | --- | --- | --- | --- | --- | --- | --- |
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|  |  | **일어** |  | **면제사유** |  |
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| **지원 동기(300자 이상)** |  |
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